

UDFN10 3x3, 0.5P (Leads 2 & 3 Tied)CASE 517CC ISSUE O АВ EXPOSED Cu MOLD CMPD **DETAIL B** ALTERNATE CONSTRUCTION PIN ONE REFERENCE С (0.17)0.15 2X \alpha 0.15 \cdot C **DETAIL B** С 0.10 △ 0.08 С C SEATING PLANE NOTE 4 DETAIL A

0.10 C A

NOTE 3

DATE 10 OCT 2011

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS. 3. DIMENSION & APPLIES TO PLATED
- TERMINAL AND IS MEASURED BETWEEN
 0.15 AND 0.30mm FROM THE TERMINAL TIP.
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

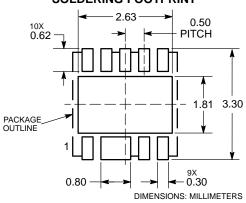
	MILLIMETERS		
DIM	MIN	MAX	
Α	0.45	0.55	
A1	0.00	0.05	
A3	0.13 REF		
b	0.15	0.25	
D	3.00 BSC		
D2	2.39	2.59	
E	3.00 BSC		
E2	1.59	1.79	
е	0.50 BSC		

L1 --- 0.15

RECOMMENDED SOLDERING FOOTPRINT*

L

е



*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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